



Materials Declaration Form

IPC	1752	Version	2
Form Type *	Distribute		
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D

** : Required Field*

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2020-04-16
Company Unique ID	NL 008751171B01		
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Contact Phone *	Refer to Supplier Comment section	Contact Email *	Refer to Supplier Comment section
Authorized Representative *	Giovanni Giacopello	Representative Title	ADG MD CHAMPION
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

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Legal Statement		
Supplier Acceptance *	true	Legal Declaration *
		Standard

Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
SMC30J16CA	8HZK*TWB019M	A	9941	2020-04-16
	Amount	UoM	Unit type	ST ECOPACK Grade
	250	mg	Each	ECOPACK® 2
Comment	ECOPACK® 2 is STMicroelectronics trade name for ROHS compliant device without Brominated and Chlorinated compound (900ppm) and without Antimony oxide flame retardant (in each organic material)			

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		
1	260	3		
Bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable	Tin (Sn), matte, annealed	Copper Alloy		



Package Designator	Size	Nbr of instances	Shape	
SOJ	4.5X2.16X3.68	2	J bend	
Comment	Package: SMC CLIP (SOD 15 NEW)			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-March 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	FALSE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	TRUE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)

QueryList : ELV directive : 2000/53/EC amended 2017/2096 _November 2017	
Query	Response
1 - Product(s) meets EU ELV requirements without any exemptions	FALSE
2 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	TRUE
Exemption Id.	Description
8e	Lead in high melting temperature type solders (i.e. lead-based alloys containing 85 % by weight or more lead)

QueryList : ELV directive : 2000/53/EC amended 2017/2096 _November 2017			
Query			Response
1 - The product does not contain identified substance from California Prop 65 List, no exposure to consumers is foreseen			FALSE
2 - The product is containing below substance(s) from California Prop 65 List, no exposure to consumers is foreseen			TRUE
Substance	amount in product (mg)	Application	ppm in product
Nickel	0.10	Die	384
Lead	3.89	Soft solder	15568

QueryList : REACH-16th July 2019				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				FALSE
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product
Lead	1000 ppm	3.89	Soft solder	15568
2 - Product(s) does not contain REACH Substances Of Very High Concern in any Embedded article nor Homogeneous Material above the limits per the definition within REACH				FALSE
CategoryLevel_Name	CategoryLevel_Threshold	Amount in Embedded Article / Homogeneous Material (mg)	Application - Article / Homogeneous Material	ppm in Article /Homogeneous Material
Lead	1000 ppm	3.89	Soft solder	924905

Material Composition Declaration :						Mfr Item Name	8HZK*TWB019M					
note : Substance present with less 0.001mg will not be declared in this document												
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	M-011 Other inorganic materials	9.525	mg	supplier	die	Silicon (Si)	7440-21-3		9.059	mg	951076	36236
				supplier	metallization	Aluminium (Al)	7429-90-5		0.053	mg	5563	212
				supplier	metallization	Gold (Au)	7440-57-5		0.038	mg	3990	152
				supplier	passivation	Nickel (Ni)	7440-02-0		0.038	mg	3990	152
				supplier	metallization	Titanium (Ti)	7440-32-6		0.008	mg	840	32
				supplier	metallization	Tungsten (W)	7440-33-7		0.013	mg	1365	52
				supplier	Passivation	Silicon Oxide	7631-86-9		0.052	mg	5459	208
				supplier	back side metallization	Aluminium (Al)	7429-90-5		0.035	mg	3675	140
				supplier	back side metallization	Gold (Au)	7440-57-5		0.012	mg	1260	48
				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.058	mg	6089	232
Leadframe & Clips	M-004 Copper and its alloys	88.360	mg	supplier	polymer die coating	Durimide	Proprietary		0.159	mg	16693	636
				supplier	alloy	Copper (Cu)	7440-50-8		88.317	mg	999513	353268
				supplier	alloy	Iron (Fe)	7439-89-6		0.009	mg	102	36
				supplier	alloy	Phosphorus metal	7723-14-0		0.030	mg	340	120
Soft solder	Solder	4.208	mg	SVHC	solder	Lead (Pb)	7439-92-1	7a-Lead in high me	3.892	mg	924905	15568
				supplier	solder	Silver (Ag)	7440-22-4		0.105	mg	24952	420
				supplier	solder	Tin (Sn)	7440-31-5		0.211	mg	50143	844
Encapsulation	M-011 Other inorganic materials	145.803	mg	supplier	mold compound	Amorphous silica	7631-86-9		129.034	mg	884989	516136
				supplier	mold compound	Epoxy Cresol Novolac	29690-82-2		8.748	mg	59999	34992
				supplier	mold compound	Phenolic resin	9003-35-4		6.562	mg	45004	26248
				supplier	mold compound	Carbon black	1333-86-4		0.583	mg	3999	2332
				supplier	mold compound	Magnesium oxide	1309-48-4		0.292	mg	2003	1168
				supplier	mold compound	Aluminium hydroxide	21645-51-2		0.292	mg	2003	1168
connections coating	Solder	2.104	mg	supplier	mold compound	Mercaptopropyl trimethoxysilane	4420-74-0		0.292	mg	2003	1168
				supplier	solder alloy	Tin (Sn)	7440-31-5		2.104	mg	1000000	8416